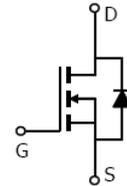


### N-Channel Enhancement Mode Field Effect Transistor

### Equivalent Circuit

- $V_{DSS} = 20\text{ V}$      $I_D = 5\text{ A}$
- $R_{DS(on)} < 30\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- $R_{DS(on)} < 40\text{ m}\Omega @ V_{GS} = 2.5\text{ V}$
- $R_{DS(on)} < 73\text{ m}\Omega @ V_{GS} = 1.8\text{ V}$



### DESCRIPTION

The 2312 uses advanced trench technology to provide excellent  $R_{DS(on)}$ . This device is suitable for use as a uni-directional or bi-directional load switch.

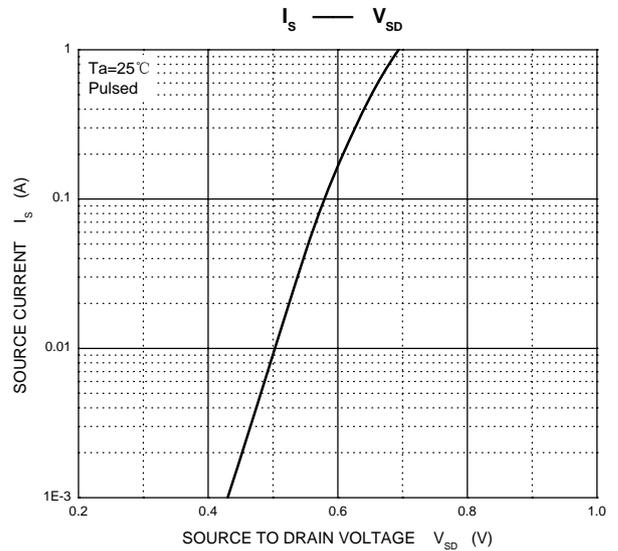
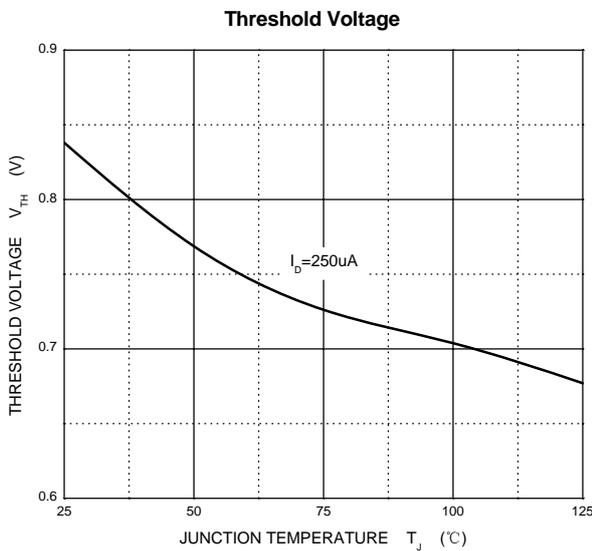
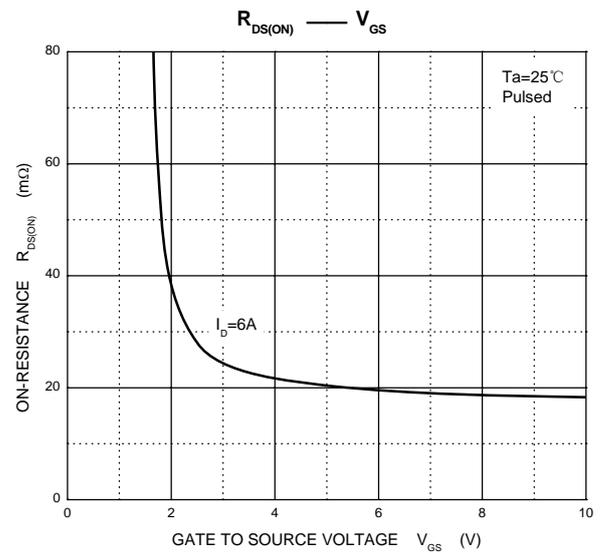
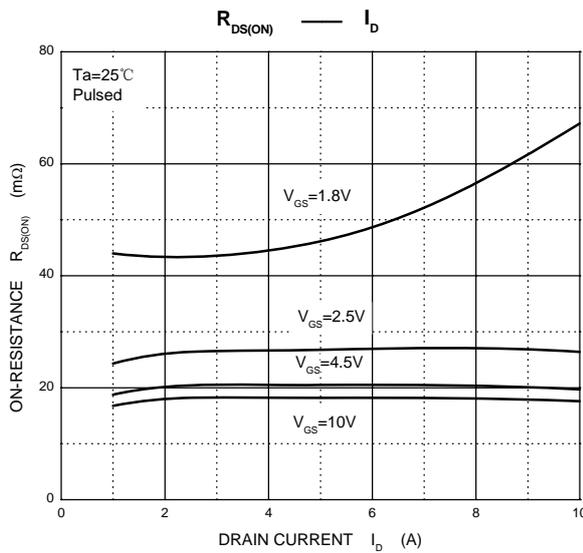
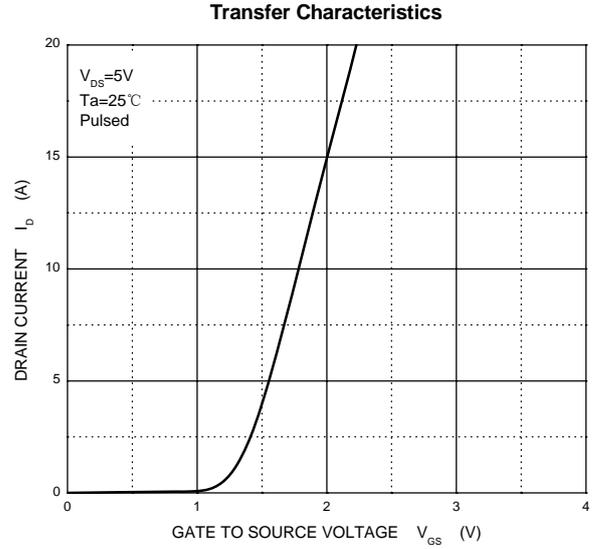
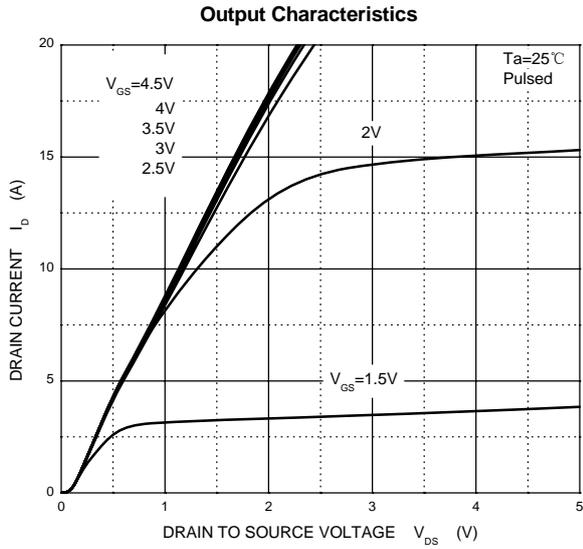
### Maximum ratings ( $T_a = 25^\circ\text{C}$ unless otherwise noted)

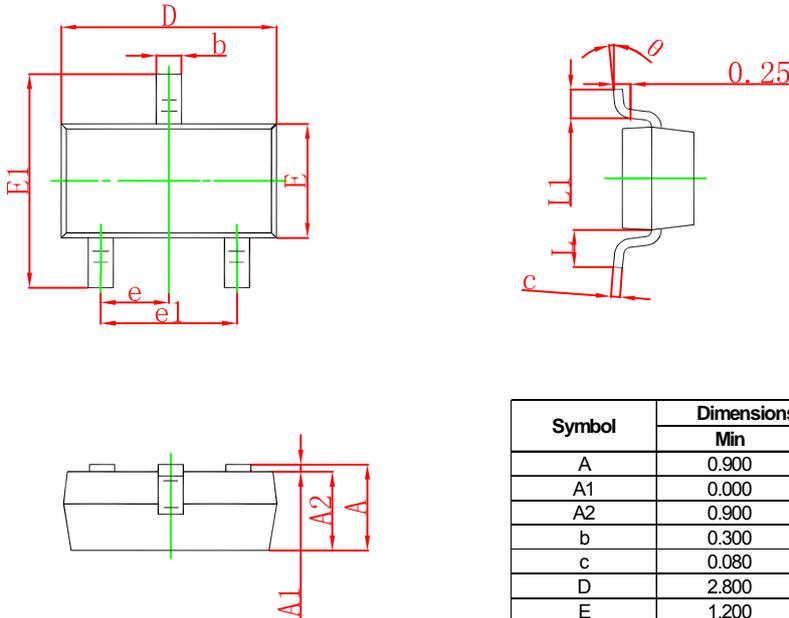
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Continuous Drain Current	$I_D$	5	A
Pulsed Drain Current	$I_{DM}$	25	
Maximum Body-Diode Continuous Current	$I_S$	2	
Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 ~ +150	

**T<sub>a</sub>=25 °C unless otherwise specified**

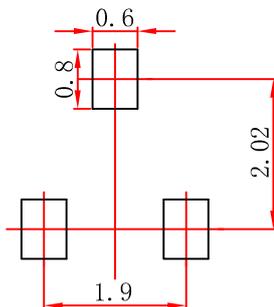
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	20			V
Gate-source leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V			1.0	μA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5	0.7	1.0	V
Drain-source on-state resistance	R <sub>Ds(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.0A		24	30	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =4.0A		30	40	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =2.0A			73	
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A		0.75	1	V
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =3.8A	4			S
<b>DYNAMIC PARAMETERS*</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f =1MHz		630		pF
Output capacitance	C <sub>oss</sub>			164		
Reverse transfer capacitance	C <sub>rss</sub>			137		
Gate resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f =1MHz		1.5		Ω
<b>SWITCHING PARAMETERS*</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =5V, V <sub>DS</sub> =10V, R <sub>L</sub> =1.7Ω, R <sub>GEN</sub> =6Ω		5.5		ns
Rise time	t <sub>r</sub>			14		
Turn-off delay time	t <sub>d(off)</sub>			29		
Fall time	t <sub>f</sub>			10.2		

\*These parameters have no way to verify.

**Typical Characteristics**


**SOT-23 Package Outline Dimensions**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

**SOT-23 Suggested Pad Layout**


- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05$ mm.
  3. The pad layout is for reference purposes only.